

SUPPLIER MUST SEND EMAIL TO EVBHOLD@QORVO.COM IF JOB IS PLACED ON HOLD

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LAYER STACK LEGEND

	Material	Layer	Thickness	Dielectric Material	Type	Comment
		SILKSCREEN_TOP			Legend	HIGH TEMPERATURE, NON-CONDUCTIVE, WHITE EPOXY BASED INK.
	Surface Material	SOLDERMASK_TOP	0.0004in	Solder Resist	Solder Mask	LPI (LIQUID PHOTO-IMAGEABLE) OR LDI (LASER DIRECT IMAGEABLE), GREEN.
	Copper	METAL1_TOP	0.0014in		Signal	FINISH THICKNESS=0.5oz COPPER CLADDING + SURFACE PLATING/VIA PLATING/FINISH
	Core		0.0100in	ROGERS 4350	Dielectric	
	Copper	METAL2_BOT	0.0014in		Signal	FINISH THICKNESS=0.5oz COPPER CLADDING + SURFACE PLATING/VIA PLATING/FINISH
	Finished board thickness: 0.0132in					

NOTES: (UNLESS OTHERWISE SPECIFIED)

1. BOARD FABRICATION METHODS MUST COMPLY WITH:
FABRICATE IN ACCORDANCE WITH IPC-6018, per IPC-6011, CLASS 2.
2. ARTWORK FORMAT: GERBER 274X
GERBER DATA SUPPLIED WITH DESIRED FINAL TRACE WIDTHS. PROCESS
COMPENSATION TRACE WIDTH ADJUSTMENTS TO BE DONE BY PCB FABRICATOR
3. FINISH PLATING:
A. METAL 1(TOP) AND METAL 2(BOTTOM):
ELECTROLYTIC FLASH GOLD
NICKEL PLATE per QQ-N-290, CLASS 1, GRADE G, 200µin. (5µm)
GOLD PLATE per ASTM B 488, TYPE III, CODE A, 3-10µin. (0.08-0.25µm)

B. METAL 1(TOP) SELECTIVE ELECTROLYTIC FLASH GOLD PLATING:
GOLD PLATE per ASTM B 488, TYPE III, CODE A, CLASS 1, 50µin. (1.27µm)
PLATING MUST BE FREE FROM CONTAMINATION, STAINS AND DEBRIS.
4. FINISHED BOARD THICKNESS: (SEE LAYER STACKUP) +/- 10%
5. COPPER IS PULLED BACK PER GERBER DATA FROM EDGE OF BOARD ON METAL 1 (TOP) AND METAL 2 (BOTTOM).
COPPER TO EDGE AT RF CONNECTORS IS CRITICAL FOR PERFORMANCE.
6. TOLERANCE: PC BOARD OUTLINE: ±0.003in.THESE VALUES ARE CRITICAL AND MUST BE INSPECTED.
7. BURRS SHALL NOT EXCEED 0.002in.
- 8 VIA PLATING/FILLING:
VIAS UNDER DUT ARE TO BE EPOXY FILLED OVER PLATED AND PLANERIZED.
ALL OTHER PLATED THRU HOLES ARE TO BE PLATED TO 0.0008 ± 0.0004in. MIN. THICKNESS.
9. CONTROLLED IMPEDANCE: CPW LAYER 1 TRACES ARE 0.015+/- 0.001, REF LAYER 2. TARGET IMPEDANCE IS 50 OHMS
+/-5%. TARGET FREQUENCY 6GHz. CORE DIELECTRIC CAN BE ADJUSTED TO OBTAIN FINISHED THICKESS. GERBER
DATA SUPPLIED WITH DESIRED FINAL TRACE WIDTHS. PROCESS COMPENSATION TRACE WIDTH ADJUSTMENT TO BE
DONE BY PCB FABRICATOR.
10. CONDUCTOR WIDTHS AND SPACING TO BE WITHIN 0.001in. OF CAD DATABASE.
11. NO ELECTRICAL TEST NEEDED.
12. NO VENDOR MARKING ALLOWED EXCEPT DATE CODE FOR TRACEABILITY.
13. SOLDERMASK IN PLATED-THRU HOLES IS ACCEPTABLE AS LONG AS IT DOES NOT EXIST ON BACKSIDE OF BOARD.
14. ALL HOLES TO BE LOCATED WITHIN ±0.003 OF CAD DATABASE.
15. DELIVER BOARDS BAGGED AS: SINGLES

* FOR MULTIPLE DRILL PROCESS JOBS SEE: *.DRL, *.DR1, *.DR2, etc.

UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN INCHES	SAP MATERIAL NUMBER: 300703					
	APPROVAL AND RELEASE RECORDS MAINTAINED IN PDE					
	DESIGNER B.HUFFIN		DATE	TITLE: QPA0022 EVALUATION PCB DESIGN PACKAGE		
	ENGR. N.NOVARIS		01/31/2022			
INTERPRET DRAWING PER ANSI/ASME Y14.5 - 2009	PDE CONTROLLED		SIZE	DOCUMENT NUMBER:	PROTOTYPE INSTANCE:	REV.
			B	QPA0022-4000	N/A	A
THIRD ANGLE PROJECTION			SHEET 1 OF 6			
DO NOT SCALE DRAWING			CAD: ALTIUM DESIGNER		SCALE: 2:1	

B

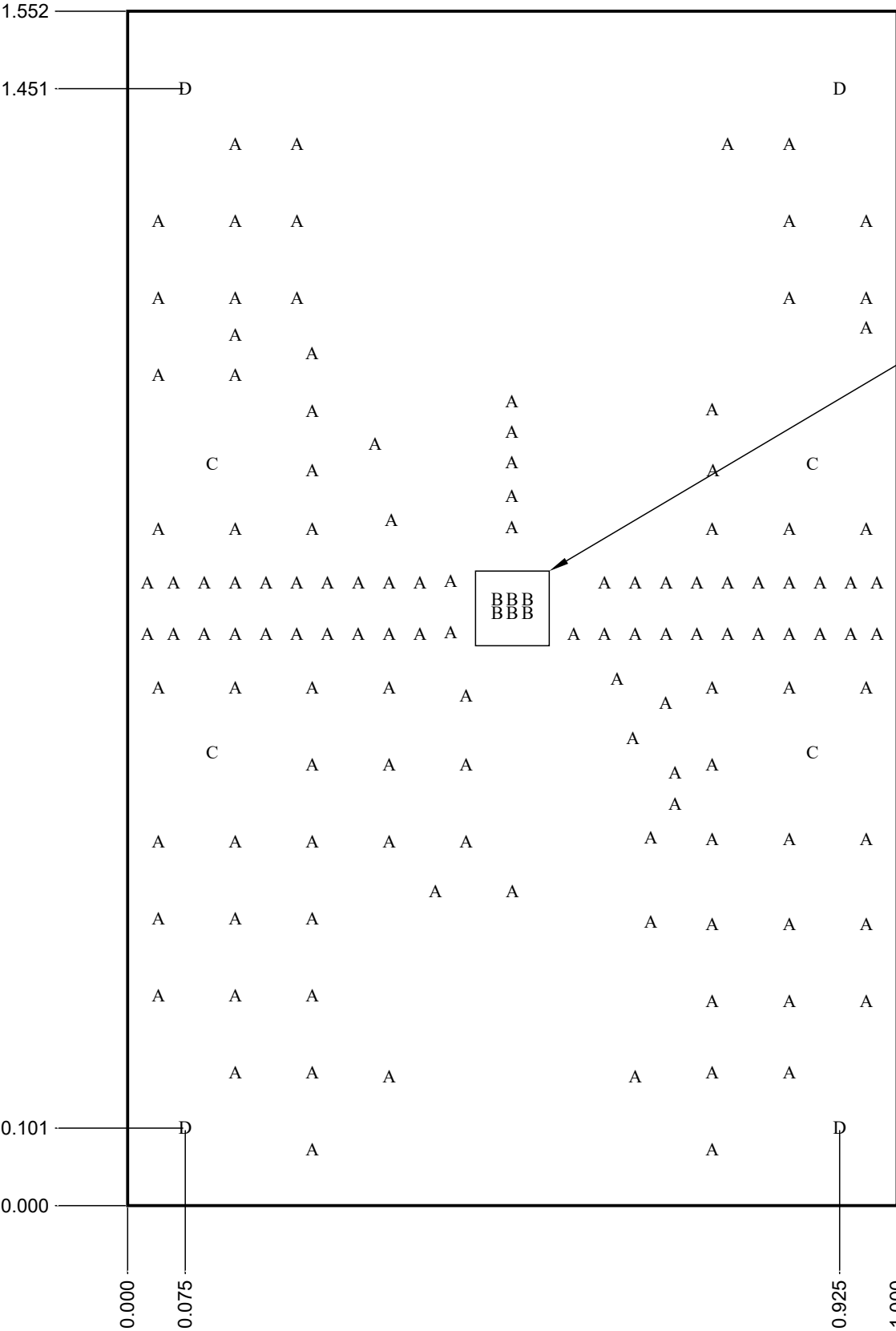
A

B

A

Drill Table

Symbol	Count	Hole Size	Plated	Drill Layer Pair
B	6	0.008	Plated	METAL1_TOP - METAL2_BOT
A	128	0.015	Plated	METAL1_TOP - METAL2_BOT
C	4	0.090	Plated	METAL1_TOP - METAL2_BOT
D	4	0.100	Plated	METAL1_TOP - METAL2_BOT
	142 Total			

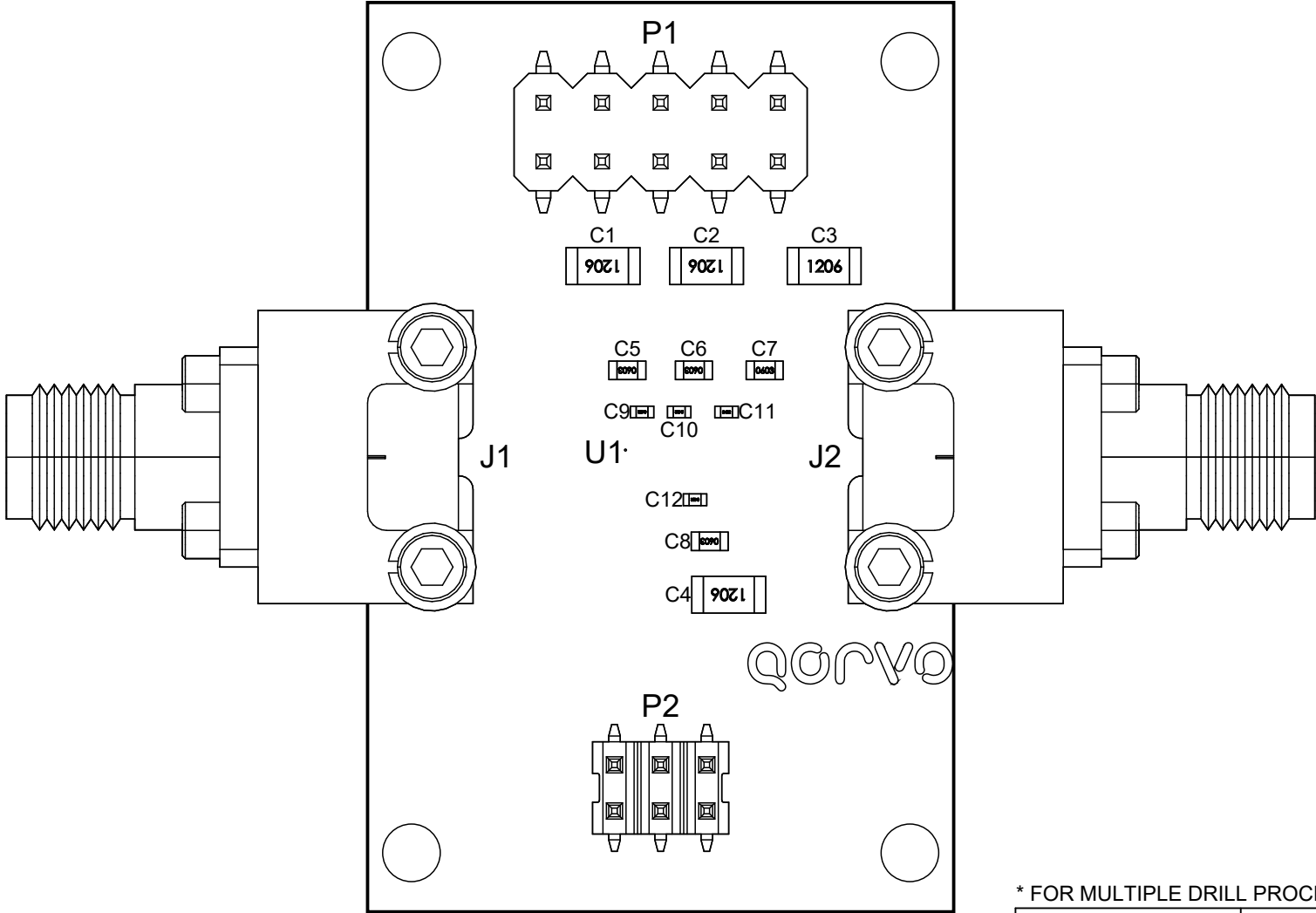


SIZE		DWG. NO.		PROTOTYPE INSTANCE:	REV.
B		QPA0022-4000		N/A	A
SHEET 2 OF 6	CAD: ALTUM DESIGNER			SCALE:	2:1


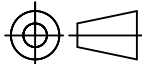
ASSEMBLY NOTES:

- 16. WORKMANSHIP & SOLDER PER IPC-A-610C, CLASS 2.
- 17. MANUFACTURERS' PART NUMBERS ARE SUBJECT TO CHANGE BY THE MANUFACTURERS FOLLOWING THE ISSUE OF THIS DOCUMENT, AND ARE THEREBY INCLUDED FOR REFERENCE ONLY. CONTACT QORVO CORORATE ENGINEERING MATERIALS WITH QUESTIONS REGARDING SPECIFIC MANUFACTURERS' PART NUMBERS.
- 18. QORVO DEVICES (DUT) MAY REQUIRE BAKING PER IPC/JEDEC J-STD-020 FOR A MINIMUM OF 24 HOURS AT 125 +5/-0 DEGREES C. ASSEMBLY MUST TAKE PLACE WITHIN 12 HOURS OF BAKE COMPLETION.
- 19. LOW TEMP SOLDER SHALL BE USED FOR ALL SMDs AND PRE-TINNING WHEN REQUIRED.
- 20. LEAD FREE (HIGH TEMP) SOLDER SHALL BE USED FOR SMA AND EDGE MOUNT CONNECTORS.

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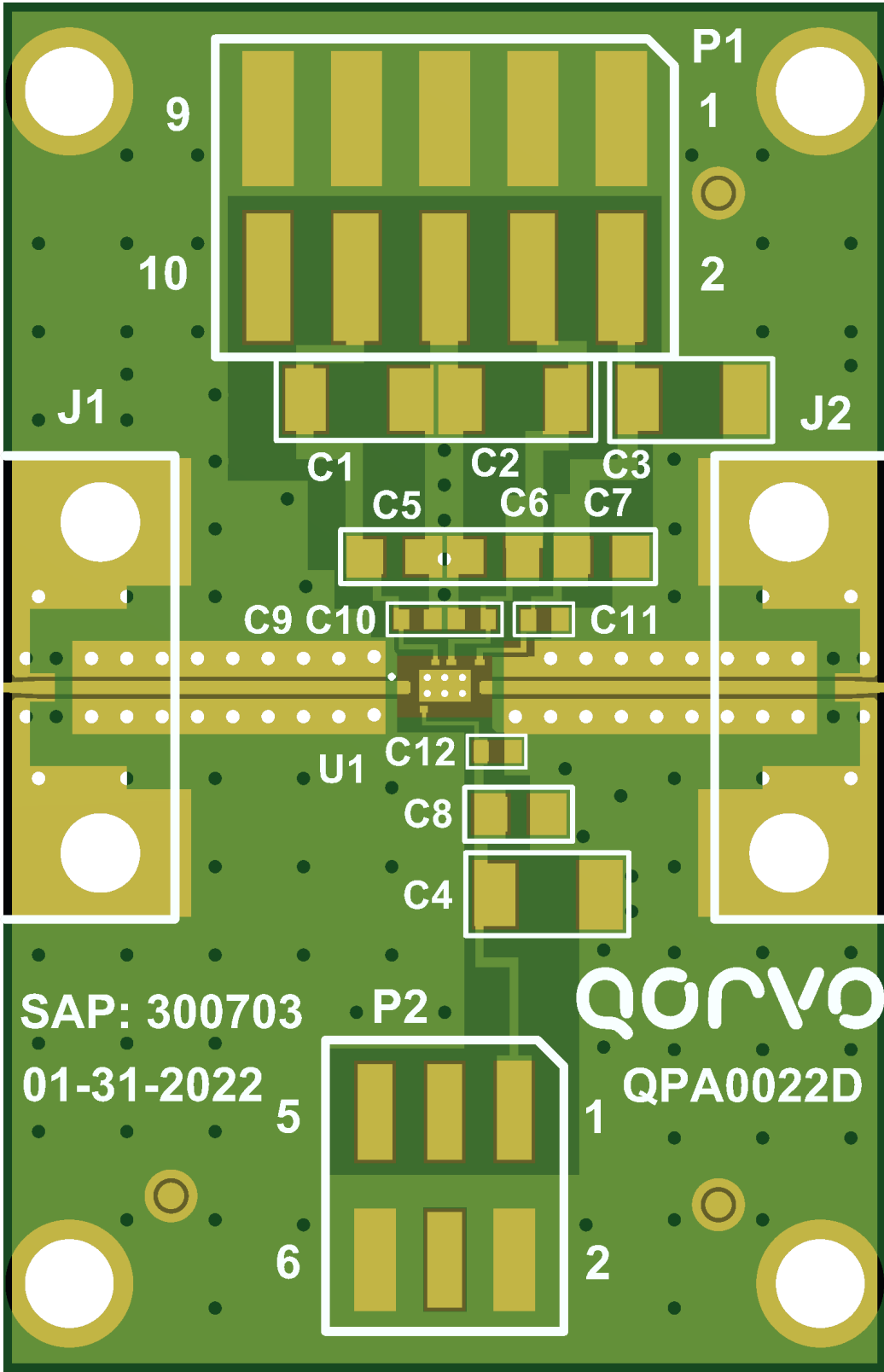
UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN INCHES		SAP MATERIAL NUMBER: 300703					
	APPROVAL AND RELEASE RECORDS MAINTAINED IN PDE		DATE				
	DESIGNER	B.HUFFIN	01/31/2022				
	ENGR.	N.NOVARIS					
INTERPRET DRAWING PER ANSI/ASME Y14.5 - 2009		PDE CONTROLLED					
				SIZE	DOCUMENT NUMBER:	PROTOTYPE INSTANCE:	REV.
THIRD ANGLE PROJECTION				B	QPA0022-4000	N/A	A
DO NOT SCALE DRAWING				SHEET 3 OF 6		CAD: ALTIVM DESIGNER	
						SCALE: 2:1	

B

B

A

A



SAP: 300703
01-31-2022

Qorvo
QPA0022D

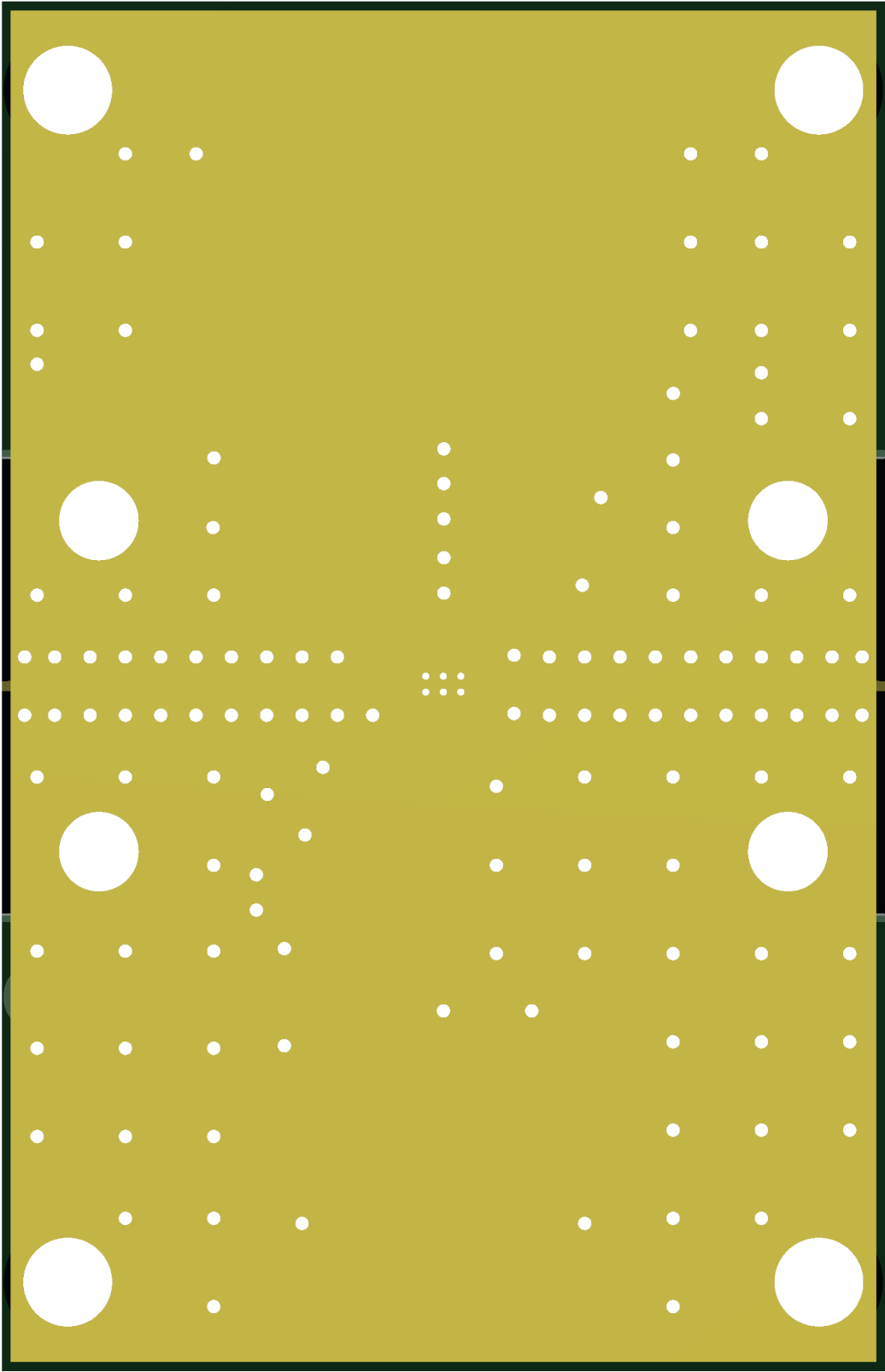
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SHEET 4 OF 6	CAD: ALTUM DESIGNER			SCALE: 2:1

B

B

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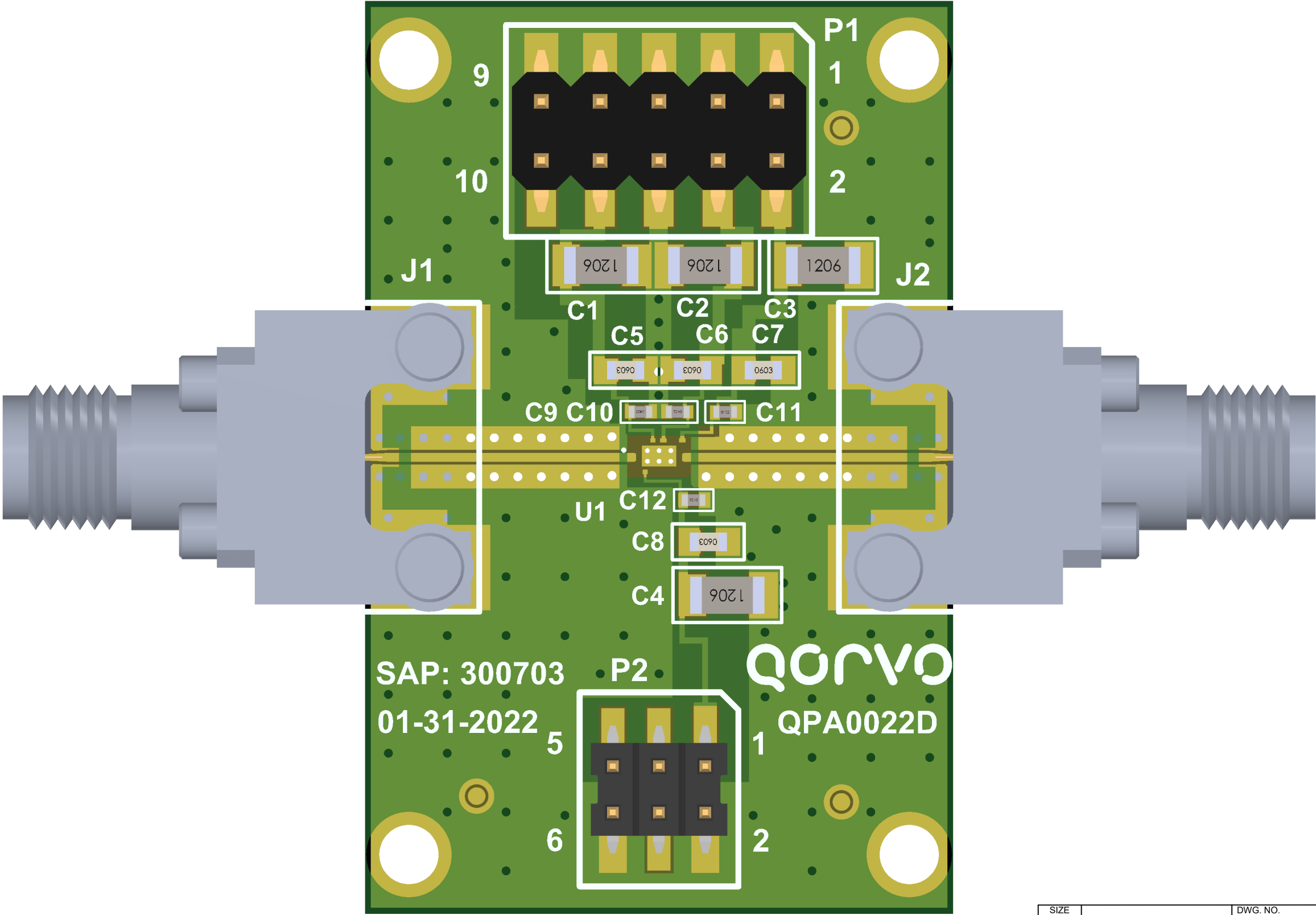
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SHEET 5 OF 6	CAD: ALTUM DESIGNER			SCALE:	2:1

B

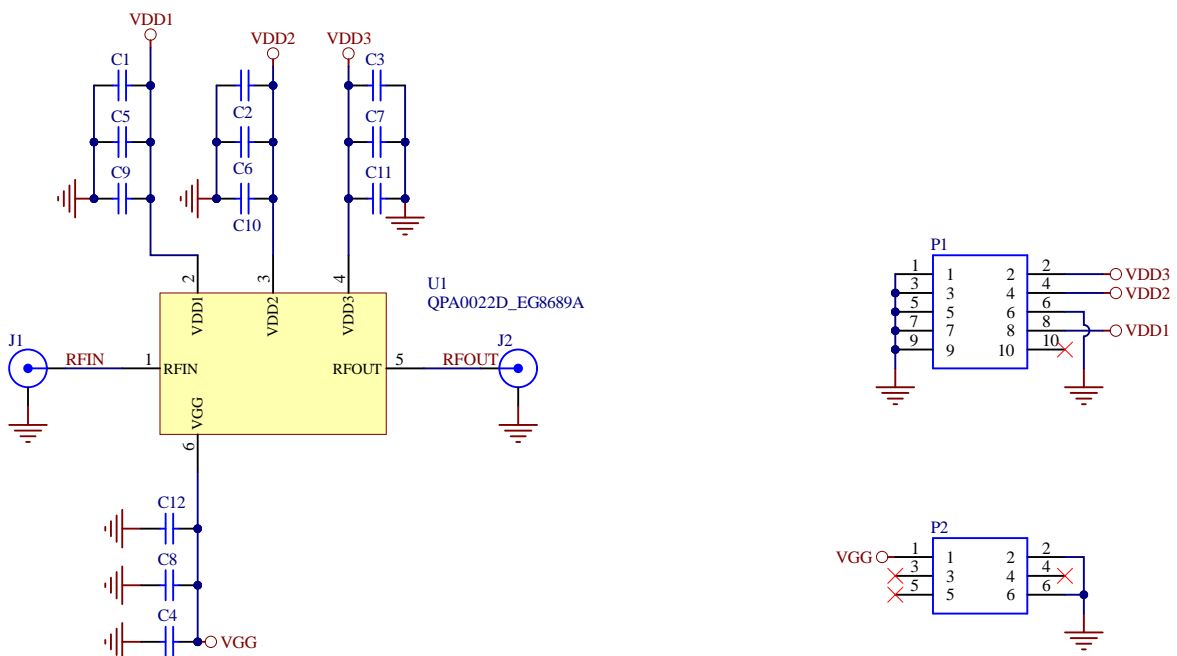
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SIZE	DWG. NO.		PROTOTYPE	REV.
B	QPA0022-4000		N/A	A
SHEET 6 OF 6	CAD: ALTIUM DESIGNER		SCALE:	2:1



QORVO_LOGO



SAP MATERIAL NUMBER: 300703		<div>QORVO</div>			
APPROVAL AND RELEASE RECORDS MAINTAINED IN PDE		DATE			
DESIGNER	J.CHAN	TITLE: QPA0022D EVALUATION PCB DESIGN PACKAGE			
ENGR.	N.NOVARIS				
PDE CONTROLLED		SIZE B	DOCUMENT NUMBER: QPA0022D-4000	PROTOTYPE INSTANCE: N/A	REV. A
		SCALE: NTS	SHEET 1 OF 1		